

Product Change Notification / SYST-13VGZP636

Date:

14-Feb-2024

Product Category:

Linear Regulators

PCN Type:

Document Change

Notification Subject:

Data Sheet - MIC39300/01/02 - 3A, Low Voltage Low Dropout Regulator

Affected CPNs:

SYST-13VGZP636_Affected_CPN_02142024.pdf SYST-13VGZP636_Affected_CPN_02142024.csv

Notification Text:

SYST-13VGZP636

Microchip has released a new Datasheet for the MIC39300/01/02 - 3A, Low Voltage Low Dropout Regulator of devices. If you are using one of these devices please read the document located at MIC39300/01/02 - 3A, Low Voltage Low Dropout Regulator.

Notification Status: Final

Description of Change:

- Removed bold from maximum value of Output Leakage Current (Page 5).
- Updated the names of Figure 2-1, Figure 2-2 and Figure 2-12.
- Updated package name in Package Types.
- Updated Section 5.0, Packaging Information and Product Identification System.

Impacts to Data Sheet: See above details.

Reason for Change: To Improve Productivity

Change Implementation Status: Complete

Date Document Changes Effective: 14 Feb 2024

NOTE: Please be advised that this is a change to the document only the product has not been changed.

Markings to Distinguish Revised from Unrevised Devices: N/A

Attachments:

MIC39300/01/02 - 3A, Low Voltage Low Dropout Regulator

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If you wish to <u>change your PCN profile, including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. Affected Catalog Part Numbers (CPN)

MIC39300-1.8WT MIC39300-1.8WU MIC39300-1.8WU-TR MIC39300-2.5WT MIC39300-2.5WU MIC39300-2.5WU-TR MIC39301-1.8WU MIC39301-1.8WU MIC39301-2.5WT MIC39301-2.5WU MIC39301-2.5WU MIC39301-2.5WU-TR MIC39302WU MIC39302WU-TR



3A, Low Voltage Low Dropout Regulator

Features

- 3.0A Minimum Guaranteed Output Current
- 550 mV Maximum Dropout Voltage over Temperature
- Ideal for 3.0V to 2.5V Conversion
- Ideal for 2.5V to 1.8V Conversion
- 1% Initial Accuracy
- Low Ground Current
- Current Limiting and Thermal Shutdown
- Reversed-Battery Protection
- Reversed-Leakage Protection
- Fast Transient Response
- TO-263 (D²Pak) and TO-220 Packaging
- TTL/CMOS Compatible Enable Pin (MIC39301/2 Only)
- Error Flag Output (MIC39301 Only)
- Adjustable Output (MIC39302 Only)

Applications

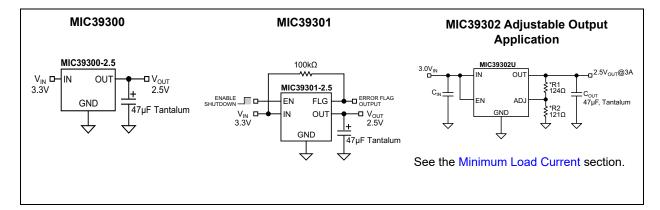
- LDO Linear Regulator for PC Add-In Cards
- · High-Efficiency Linear Power Supplies
- SMPS Post Regulator
- Multimedia and PC Processor Supplies
- Low Voltage Microcontrollers
- StrongARM Processor Supply

General Description

The MIC39300, MIC39301, and MIC39302 are 3.0A low-dropout linear voltage regulators that provide a low voltage, high-current output with a minimum of external components. Utilizing Microchip's proprietary Super β eta PNP pass element, the MIC39300/1/2 offers extremely low dropout (typically 385 mV at 3.0A) and low ground current (typically 45 mA at 3.0A).

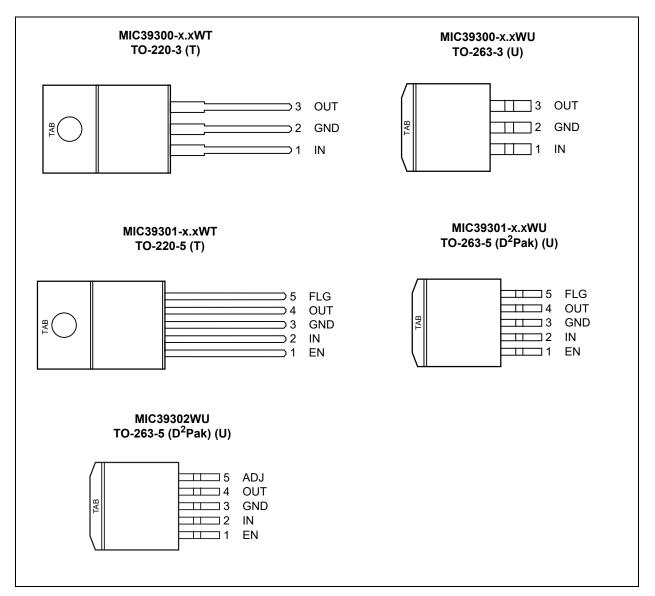
The MIC39300/1/2 are ideal for PC add-in cards that need to convert from standard 3.3V to 2.5V or 2.5V to 1.8V. A guaranteed maximum dropout voltage of 550 mV over all operating conditions allows the MIC39300/1/2 to provide 2.5V from a supply as low as 3V, and 1.8V from a supply as low as 2.5V. The MIC39300/1/2 also have fast transient response for heavy switching applications. The device requires only 47 μ F of output capacitance to maintain stability and achieve fast transient response.

The MIC39300/1/2 are fully protected with overcurrent limiting, shutdown, reversed-battery thermal protection, reversed-leakage protection, and reversed-lead insertion. The MIC39301 offers a TTL-logic compatible enable pin and an error flag that indicates undervoltage and overcurrent conditions. Offered in fixed voltages, the MIC39300/1 come in the TO-220 and TO-263 (D²Pak) packages and are an ideal upgrade to older, NPN-based linear voltage regulators. The MIC39302 adjustable option allows programming the output voltage anywhere between 1.24V and 15.5V and is offered in a 5-Pin TO-263 (D²Pak) package.

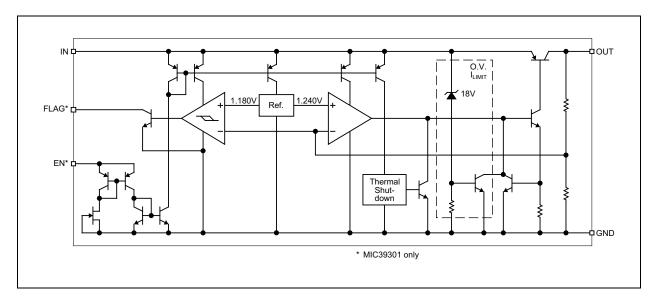


Typical Application Circuits

Package Types



Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

| Supply Voltage (V _{IN}) | -20V to +20V |
|-----------------------------------|--------------|
| Enable Voltage (V _{EN}) | |
| ESD Rating (Note 1) | |

Operating Ratings ‡

| Supply Voltage (V _{IN}) | +2.5V to +16V |
|--|---------------|
| Enable Voltage (V _{EN}) | |
| Maximum Power Dissipation (P _{D(max)}) | |

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability. Specifications are for packaged product only.

‡ Notice: The device is not guaranteed to function outside its operating ratings.

- Note 1: Devices are ESD sensitive. Handling precautions are recommended.
 - **2:** $P_{D(max)} = (T_{J(max)} T_A) \div \theta_{JA}$, where θ_{JA} depends upon the printed circuit layout. See the Application Information section.

ELECTRICAL CHARACTERISTICS

| Parameter | Symbol | Min. | Тур. | Max. | Units | Conditions |
|--|-------------------------------------|------|------|------|--------|--|
| | | -1 | | 1 | % | I _{OUT} =10 mA |
| Output Voltage | V _{OUT} | -2 | _ | 2 | % | 10 mA \leq I _{OUT} \leq 3A,V _{OUT} + 1V \leq V _{IN} \leq 8V |
| Line Regulation | $\Delta V_{OUT} / \Delta V_{IN}$ | _ | 0.06 | 0.5 | % | $I_{OUT} = 10 \text{ mA}, V_{OUT} + 1V \le V_{IN} \le 8V$ |
| Load Regulation | ΔV _{OUT} /V _{OUT} | _ | 0.2 | 1 | % | $V_{IN} = V_{OUT} + 1V,10 \text{ mA} \le I_{OUT} \le 3A$ |
| Output Voltage Temperature Coefficient (Note 1) | ΔV _{OUT} /ΔT | _ | 20 | 100 | ppm/°C | _ |
| | | — | 65 | 200 | mV | I _{OUT} = 100 mA, ΔV _{OUT} = -1% |
| Dropout Voltage (Note 2), (Note 4) | V _{DO} | | 185 | — | mV | I _{OUT} = 750 mA, ΔV _{OUT} = -1% |
| | | _ | 250 | — | mV | I _{OUT} = 1.5A, ΔV _{OUT} = -1% |
| | | | 385 | 550 | mV | I _{OUT} = 3A, ΔV _{OUT} = -1% |
| | I _{GND} | _ | 10 | 20 | mA | I _{OUT} = 750 mA, V _{IN} = V _{OUT} + 1V |
| Ground Current (Note 3) | | _ | 17 | | mA | I _{OUT} = 1.5A, V _{IN} = V _{OUT} + 1V |
| | | | 45 | _ | mA | I_{OUT} = 3A, V_{IN} = V_{OUT} + 1V |
| Dropout Ground Pin Current | I _{GND(do)} | — | 6 | — | mA | V _{IN} ≤ V _{OUT} (nominal) -0.5V, I _{OUT} = 10 mA |
| Current Limit | I _{OUT(lim)} | | 4.5 | — | Α | V _{OUT} = 0V, V _{IN} = V _{OUT} + 1V |
| Enable Input (MIC39301) | | | | | | |
| Enchla Input Valtaga | V | _ | — | 0.8 | V | Logic low (OFF) |
| Enable Input Voltage | V _{EN} | 2.5 | — | — | V | Logic high (ON) |
| | | _ | 15 | 75 | μA | V _{EN} = 2.5V |
| Enable Input Current | I _{IN} | — | — | 90 | μA | V _{EN} = 16V |
| | | _ | — | 4 | μA | V _{EN} = 0.8V |

| Parameter | Symbol | Min. | Тур. | Max. | Units | Conditions |
|---|------------------------|-------|-------|-------|--------|---|
| Shutdown Output Current (Note 5) | I _{OUT(shdn)} | _ | 10 | 20 | μA | _ |
| Flag Output (MIC39301) | | | | | | |
| Output Leakage Current | | — | 0.01 | 1 | | V _{IN} = 16V |
| Output Leakage Current | ^I FLG(leak) | — | _ | 2 | μA | V _{IN} = 10V |
| Output Low Voltage (Note 4) | M | — | 220 | 300 | mV | V _{IN} = 2.50V, I _{OL} = 250 μA |
| Output Low Voltage (Note 4) | V _{FLG(do)} | _ | _ | 400 | mv | — |
| Low Threshold | | 93 | — | _ | % | % of V _{OUT} |
| High Threshold | V _{FLG} | _ | _ | 99.2 | % | % of V _{OUT} |
| Hysteresis | | | 1 | _ | % | — |
| Reference (Adjust Pin) - MIC | 39302 Only | | | | | |
| | Ň | 1.228 | 1.240 | 1.252 | V | |
| Reference Voltage | V _{ADJ} | 1.215 | | 1.265 | v | — |
| Reference Voltage Temp. Coefficient (Note 6) | V _{TC} | _ | 20 | _ | ppm/°C | _ |
| Adjust Die Dies Current | | — | 40 | 80 | - 1 | |
| Adjust Pin Bias Current | I _{ADJ} | — | | 120 | nA | - |
| Adjust Pin Bias Current Temp. Coefficient | I _{TC} | _ | 0.1 | _ | nA/°C | _ |

Electrical Characteristics: $T_J = 25^{\circ}C$, **Bold** values indicate $-40^{\circ}C \le T_J \le +125^{\circ}C$; unless otherwise specified.

1: Output voltage temperature coefficient is ΔV_{OUT} (worst case) ÷ ($T_{J(max)} - T_{J(min)}$) where $T_{J(max)}$ is +125°C and $T_{J(min)}$ is -40°C.

2: V_{DO} = V_{IN} - V_{OUT} when V_{OUT} decreases to 99% of its nominal output voltage with V_{IN} = V_{OUT} + 1V. For output voltages below 2.5V, dropout voltage is the input-to-output voltage differential with the minimum input voltage being 2.5V. Minimum input operating voltage is 2.5V.

 $3: I_{\rm IN} = I_{\rm GND} + I_{\rm OUT}.$

- **4:** For a 1.8V device, V_{IN} = 2.5V.
- 5: $V_{EN} \le 0.8V$, $V_{IN} \le 8V$, and $V_{OUT} = 0V$.
- 6: Thermal regulation is defined as the change in output voltage at a time t after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a 200 mA load pulse at $V_{IN} = 8V$ for t = 10 ms.

TEMPERATURE SPECIFICATIONS (Note 1)

| Parameters | Sym. | Min. | Тур. | Max. | Units | Conditions | | | |
|---|-----------------|------|------|------|-------|-------------------|--|--|--|
| Temperature Ranges | | | | | | | | | |
| Lead Temperature | _ | _ | | 260 | °C | Soldering, 5 sec. | | | |
| Junction Operating Temperature Range | TJ | -40 | — | +125 | °C | — | | | |
| Storage Temperature Range | Τ _S | -65 | — | +150 | °C | — | | | |
| Package Thermal Resistances | | | | | | | | | |
| Thermal Resistance TO-263 | θ_{JC} | _ | 2 | _ | °C/W | — | | | |
| Thermal Resistance TO-220 | θ _{JC} | — | 2 | — | °C/W | — | | | |

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e., T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +125°C rating. Sustained junction temperatures above +125°C can impact the device reliability.

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

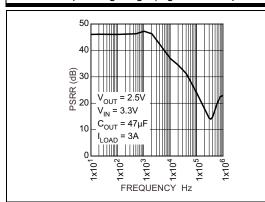


FIGURE 2-1: Power Supply Ripple Rejection vs. Frequency.

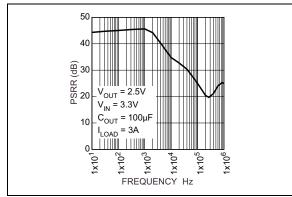
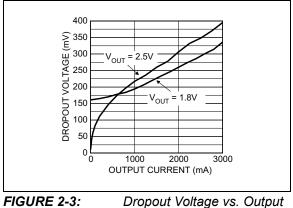


FIGURE 2-2: Power Supply Ripple Rejection vs. Frequency.



Current.

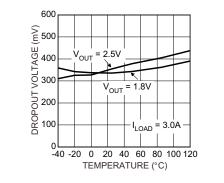


FIGURE 2-4: Dropout Voltage vs. Temperature.

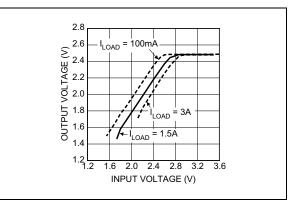
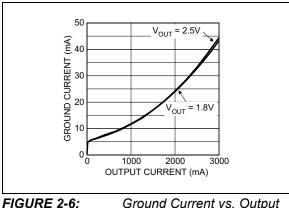


FIGURE 2-5:

Dropout Characteristics.



Current.

Ground Current vs. Output

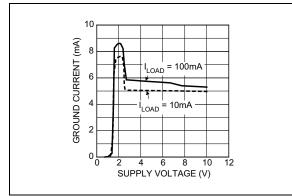


FIGURE 2-7: Ground Current vs. Supply Voltage.

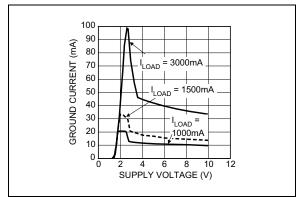


FIGURE 2-8: Ground Current vs. Supply Voltage.

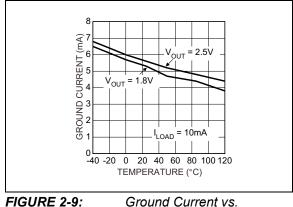


FIGURE 2-9: Temperature.

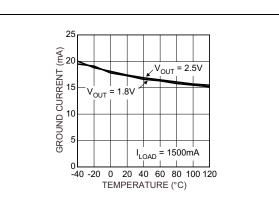


FIGURE 2-10: Ground Current vs. Temperature.

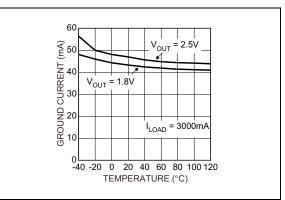


FIGURE 2-11: Ground Current vs. Temperature.

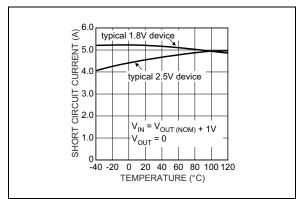


FIGURE 2-12: Temperature.

Short Circuit Current vs.

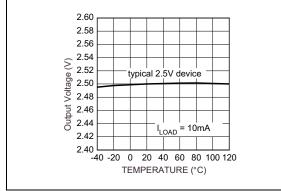


FIGURE 2-13: Output Voltage vs. Temperature.

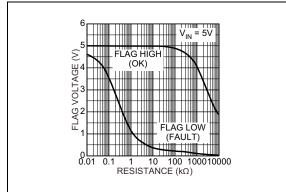
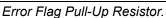


FIGURE 2-14:



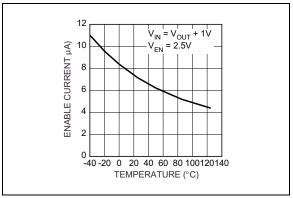


FIGURE 2-15: Enable Current vs. Temperature.

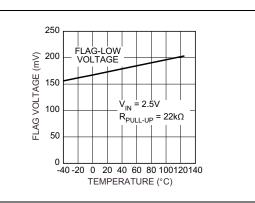


FIGURE 2-16: Flag-Low Voltage vs. Temperature.

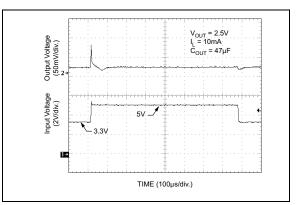


FIGURE 2-17: Line Transient Response.

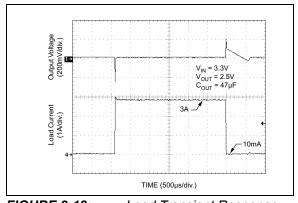


FIGURE 2-18: Load Transient Response.

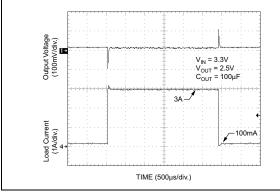


FIGURE 2-19:

Load Transient Response.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

| Pin Number MIC39300 | Pin Number MIC39301 | Pin Number MIC39302 | Pin Name | Description |
|------------------------|------------------------|------------------------|-------------|---|
| — | 1 | 1 | EN | Enable (Input): TTL/CMOS compatible input. Logic-high = enable; logic-low or open = shutdown. |
| 1 | 2 | 2 | IN | Unregulated Input: +16V maximum supply. |
| 2, TAB | 3, TAB | 3, TAB | GND | Ground: Ground pin and TAB are internally connected. |
| 3 | 4 | 4 | OUT | Regulator Output. |
| _ | 5 | _ | FLG | Error Flag (Output): Open-collector indicates an output fault condition. Active low. |
| _ | _ | 5 | ADJ | Adjustable Regulator Feedback Input: Connect to the resistor voltage divider that is placed from OUT to GND in order to set the output voltage. |

TABLE 3-1: PIN FUNCTION TABLE

4.0 APPLICATION INFORMATION

The MIC39300/1/2 are high-performance, low-dropout voltage regulators suitable for moderate to high-current voltage regulator applications. Its 550 mV dropout voltage at full load makes it especially valuable in battery-powered systems and as a high-efficiency noise filter in post-regulator applications. Unlike older NPN-pass transistor designs, where the minimum dropout voltage is limited by the base-to-emitter voltage drop and collector-to-emitter saturation voltage, dropout performance of the PNP output of these devices is limited only by the low V_{CE} saturation voltage.

A trade-off for the low dropout voltage is a varying base drive requirement. Microchip's Super β eta PNP process reduces this drive requirement to only 2% to 5% of the load current.

The MIC39300/1/2 regulators are fully protected from damage due to fault conditions. Current limiting is provided. This limiting is linear; output current during overload conditions is constant. Thermal shutdown disables the device when the die temperature exceeds the maximum safe operating temperature. Transient protection allows device (and load) survival even when the input voltage spikes above and below nominal. The output structure of these regulators allows voltages in excess of the desired output voltage to be applied without reverse current flow.

4.1 Thermal Design

Linear regulators are simple to use. The most complicated design parameters to consider are thermal characteristics. Thermal design requires four application-specific parameters:

- Maximum ambient temperature (T_A)
- Output Current (I_{OUT})
- Output Voltage (V_{OUT})
- Input Voltage (V_{IN})
- Ground Current (I_{GND})

Calculate the power dissipation of the regulator from these numbers and the device parameters from this data sheet, where the ground current is taken from the data sheet.

EQUATION 4-1:

$$P_D = (V_{IN} - V_{OUT})I_{OUT} + V_{IN} \times I_{GND}$$

The heat sink thermal resistance is determined by:

EQUATION 4-2:

$$\begin{split} \theta_{SA} &= \frac{T_{J(MAX)} - T_A}{P_D} - (\theta_{JC} + \theta_{CS}) \end{split}$$
 Where:
$$T_{J(MAX)} \leq 125^{\circ}\text{C} \\ \theta_{CS} & \text{Between 0}^{\circ}\text{C/W} \text{ and } 2^{\circ}\text{C/W} \end{split}$$

The heat sink may be significantly reduced in applications where the minimum input voltage is known and is large compared with the dropout voltage. Use a series input resistor to drop excessive voltage and distribute the heat between this resistor and the regulator. The low dropout properties of Microchip's Super β eta PNP regulators allow significant reductions in regulator power dissipation and the associated heat sink without compromising performance. When this technique is employed, a capacitor of at least 1.0 μ F is needed directly between the input and regulator ground.

Refer to Application Note 9 for further details and examples on thermal design and heat sink specification.

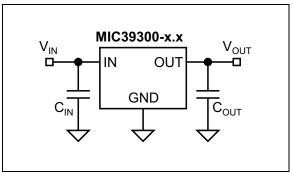


FIGURE 4-1: Capacitor Requirements.

4.2 Output Capacitor

The MIC39300/1/2 requires an output capacitor to maintain stability and improve transient response. Proper capacitor selection is important to ensure proper operation. The MIC39300/1/2 output capacitor selection is dependent upon the ESR (equivalent series resistance) of the output capacitor to maintain stability. When the output capacitor is 47 μ F or greater, the output capacitor should have less than 1 Ω of ESR. This will improve transient response as well as promote stability. Ultra low ESR capacitors, such as ceramic chip capacitors may promote instability. These very low ESR levels may cause an oscillation and/or underdamped transient response. A low-ESR solid tantalum capacitor works extremely well and provides

good transient response and stability over temperature. Aluminum electrolytics can also be used, as long as the ESR of the capacitor is < 1Ω .

The value of the output capacitor can be increased without limit. Higher capacitance values help to improve transient response and ripple rejection and reduce output noise.

4.3 Input Capacitor

An input capacitor of 1 μ F or greater is recommended when the device is more than 4 inches away from the bulk AC supply capacitance or when the supply is a battery. Small, surface mount, ceramic chip capacitors can be used for bypassing. Larger values will help to improve ripple rejection by bypassing the input to the regulator, further improving the integrity of the output voltage.

4.4 Transient Response and 3.3V to 2.5V and 2.5V to 1.8V Conversions

The MIC39300/1/2 has excellent transient response to variations in input voltage and load current. The device has been designed to respond quickly to load current variations and input voltage variations. Large output capacitors are not required to obtain this performance. A standard 47 μ F output capacitor, preferably tantalum, is all that is required. Larger values help to improve performance even further.

By virtue of its low dropout voltage, this device does not saturate into dropout as readily as similar NPN-based designs. When converting from 3.3V to 2.5V or 2.5V to 1.8V, the NPN-based regulators are already operating in dropout, with typical dropout requirements of 1.2V or greater. To convert down to 2.5V without operating in dropout, NPN-based regulators require an input voltage of 3.7V at the very least. The MIC39300/1 regulator will provide excellent performance with an input as low as 3.0V or 2.5V. This gives the PNP-based regulators a distinct advantage over older, NPN-based linear regulators.

4.5 Minimum Load Current

The MIC39300/1/2 regulators are specified between finite loads. If the output current is too small, leakage currents dominate and the output voltage rises. A 10 mA minimum load current is necessary for proper regulation.

4.6 Error Flag

The MIC39301 version features an error flag circuit that monitors the output voltage and signals an error condition when the voltage drops 5% below the nominal output voltage. The error flag is an open-collector output that can sink 10 mA during a fault condition. Low output voltage can be caused by a number of problems, including an overcurrent fault (device in current limit) or low input voltage. The flag is inoperative during overtemperature shutdown.

When the error flag is not used, it is best to leave it open. A pull-up resistor from FLG to either V_{IN} or V_{OUT} is required for proper operation.

4.7 Enable Input

The MIC39301/2 feature an enable input for on/off control of the device. The enable input's shutdown state draws "zero" current (only microamperes of leakage). The enable input is TTL/CMOS compatible for simple logic interface, but can be connected to up to 20V. When enabled, it draws approximately 15 µA.

4.8 Adjustable Regulator Design

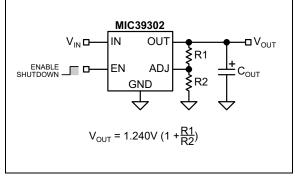


FIGURE 4-2: Adjustable Regulator with Resistors.

The MIC39302 allows programming the output voltage anywhere between 1.24V and 15.5V. Two resistors are used. The resistor values are calculated by:

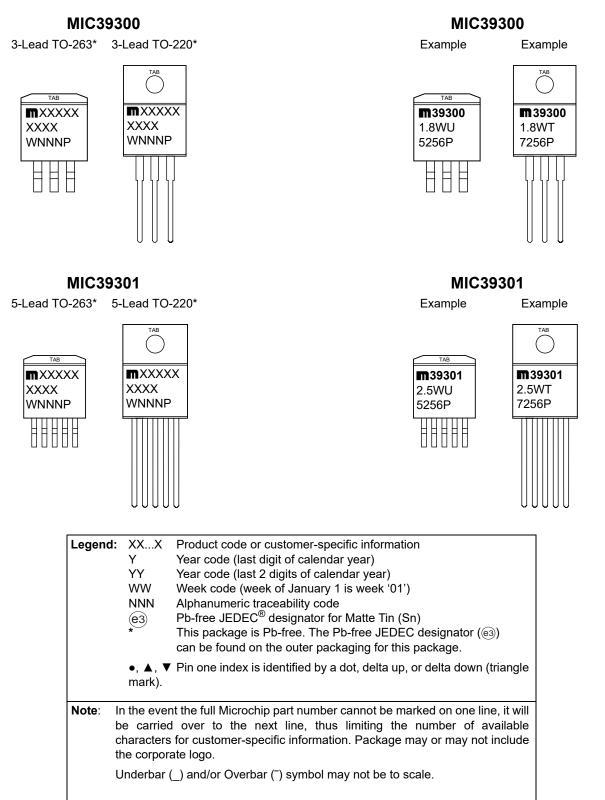
EQUATION 4-3:

$$R1 = R2\left(\frac{V_{OUT}}{1.240} - 1\right)$$

Where V_{OUT} is the desired output voltage. Figure 4-2 shows the component definition. Applications with widely varying load currents may scale the resistors to draw the minimum load current required for proper operation (see the Minimum Load Current section).

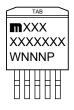
5.0 PACKAGING INFORMATION

5.1 Package Marking Information



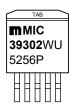
MIC39302

5-Lead TO-263*



MIC39302

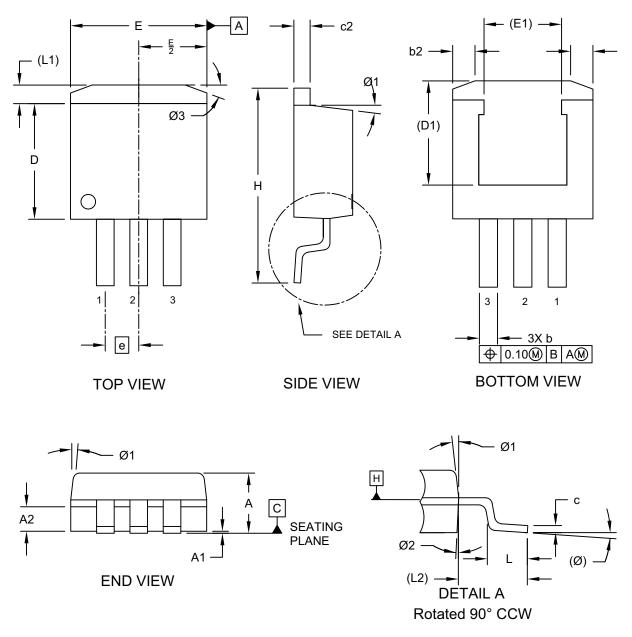
Example



| Legend | : XXX Y YY WW NNN (€3) * •, ▲, ♥ mark). | Product code or customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC [®] designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator (@3) can be found on the outer packaging for this package. ' Pin one index is identified by a dot, delta up, or delta down (triangle |
|--------|---|--|
| | be carried characters the corpor | nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available of or customer-specific information. Package may or may not include ate logo. (_) and/or Overbar (⁻) symbol may not be to scale. |

3-Lead Transistor Outline (9GA) - [TO-263]

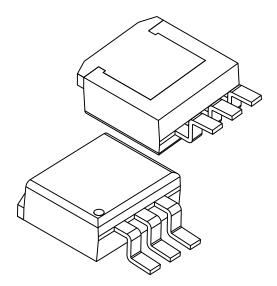
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-1169 Rev B Sheet 1 of 2

3-Lead Transistor Outline (9GA) - [TO-263]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



| | MILLIMETERS | | | |
|-----------------------|-------------|----------|----------|-------|
| Dimension | Min | Nom | Max | |
| Number of Leads | N | | 3 | |
| Pitch | е | | 2.54 BSC | |
| Overall Height | A | 4.32 | _ | 4.60 |
| Seating Plane Height | A1 | _ | _ | 0.30 |
| Lead Width | b | 1.19 | _ | 1.34 |
| Thermal Pad Cut Back | b2 | 1.39 | _ | 1.90 |
| Lead Thickness | С | 0.30 | - | 0.58 |
| Thermal Pad Thickness | c2 | 1.14 | - | 1.39 |
| Molded Body Length | D | 8.38 | — | 9.16 |
| Thermal Pad Length | D1 | 7.69 REF | | |
| Total Width | E | 10.05 | _ | 10.66 |
| Thermal Pad Width | E1 | | 6.50 REF | |
| Overall Length | Н | 14.60 | _ | 15.87 |
| Foot Length | L | 2.28 | _ | 2.79 |
| Tab Length | L1 | 1.14 | _ | 1.67 |
| Lead Length | L2 | | 5.05 REF | |
| Foot Angle | θ | 0° | _ | 8° |
| Mold Draft Angle | θ1 | 3° | - | 10° |
| Mold Draft Angle | θ2 | 1° | - | 7° |
| Thermal Tab Angle | θ3 | 18° | - | 22° |

Notes:

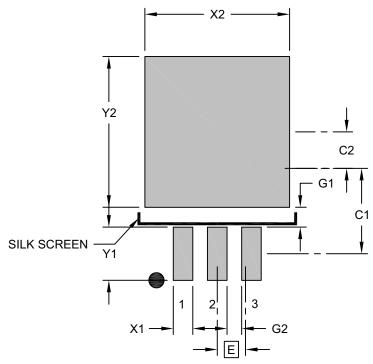
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances. REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1169 Rev B Sheet 2 of 2

3-Lead Transistor Outline (9GA) - [TO-263]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

| | N | IILLIMETER | S | |
|---------------------------------|--------|-------------------|----------|-------|
| Dimension | Limits | MIN | NOM | MAX |
| Contact Pitch | E | | 2.54 BSC | |
| Center Pad Width | X2 | | | 10.75 |
| Center Pad Length | Y2 | | | 11.20 |
| Contact Pad Spacing | C1 | | 6.35 | |
| Contact Pad Spacing | C2 | | 2.70 | |
| Contact Pad Width (X3) | X1 | | | 1.45 |
| Contact Pad Length (X3) | Y1 | | | 3.90 |
| Contact Pad to Center Pad (X3) | G1 | 1.47 | | |
| Contact Pad to Contact Pad (X2) | G2 | 1.09 | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

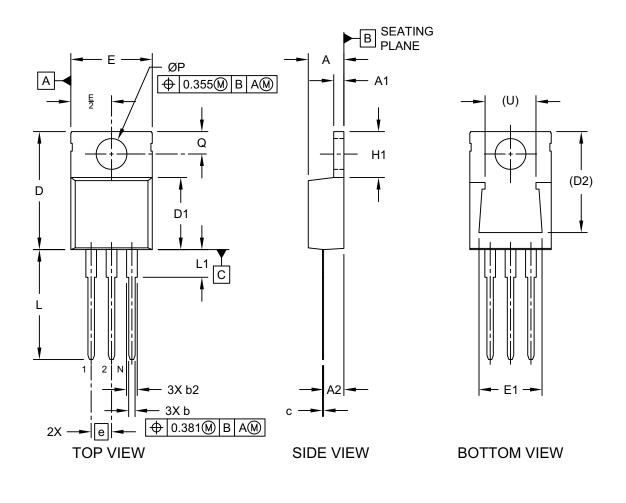
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

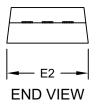
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-3169 Rev B

3-Lead Transistor Outline Package (AB) - [TO-220]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

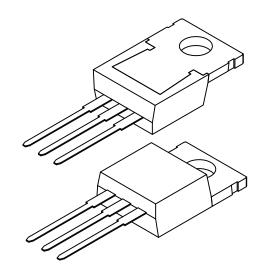




Microchip Technology Drawing C04-034-AB Rev C Sheet 1 of 2

3-Lead Transistor Outline Package (AB) - [TO-220]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



| | Units | | | | |
|--------------------------|------------------|--------|----------|--------|--|
| | Dimension Limits | MIN | NOM | MAX | |
| Number of Terminals | N | 3 | | | |
| Terminal Pitch | е | | 2.54 BSC | - | |
| Overall Height | A | 4.064 | 4.445 | 4.826 | |
| Tab Thickness | A1 | 1.143 | 1.270 | 1.397 | |
| Base to Lead | A2 | 2.032 | 2.540 | 3.048 | |
| Terminal Width | b | 0.635 | 0.826 | 1.016 | |
| Shoulder Width | b2 | 1.143 | 1.334 | 1.524 | |
| Terminal Thickness | С | 0.305 | 0.432 | 0.559 | |
| Overall Length | D | 13.730 | 14.730 | 15.730 | |
| Molded Package Length | D1 | 8.850 | 9.000 | 9.150 | |
| Exposed Pad Length | D2 | | 12.6 REF | | |
| Overall Width | E | 9.652 | 10.160 | 10.668 | |
| Exposed Pad Width | U | | 6.35 REF | | |
| Exposed Pad Width | E1 | 6.858 | 7.874 | 8.890 | |
| Body Width | E2 | 9.779 | 10.224 | 10.668 | |
| Tab Length | H1 | 5.842 | 6.350 | 6.858 | |
| Terminal Length | L | 12.700 | 13.716 | 14.732 | |
| Terminal Shoulder Length | L1 | 3.050 | 3.455 | 3.860 | |
| Mounting Hole Diameter | P | 3.708 | 3.835 | 3.962 | |
| Mounting Hole Center | Q | 2.540 | 2.794 | 3.048 | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

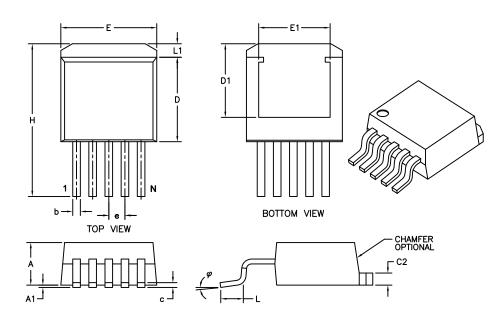
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-034-AB Rev C Sheet 2 of 2

5-Lead Plastic (ET) [DDPAK]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



| | | INCHES | | |
|-----------------------|------------------|--------|----------|------|
| Dimension | Dimension Limits | | | |
| Number of Pins | Ν | | 5 | |
| Pitch | е | | .067 BSC | |
| Overall Height | Α | .160 | - | .190 |
| Standoff § | A1 | .000 | - | .010 |
| Overall Width | E | .380 | - | .420 |
| Exposed Pad Width | E1 | .245 | - | - |
| Molded Package Length | D | .330 | - | .380 |
| Overall Length | Н | .549 | - | .625 |
| Exposed Pad Length | D1 | .270 | - | - |
| Lead Thickness | С | .014 | - | .029 |
| Pad Thickness | C2 | .045 | - | .065 |
| Lead Width | b | .020 | - | .039 |
| Foot Length | L | .068 | - | .110 |
| Pad Length | L1 | - | - | .067 |
| Foot Angle | φ | 0° | - | 8° |

Notes:

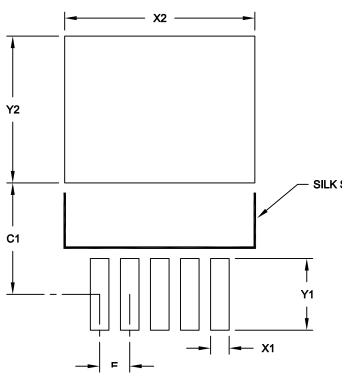
- 1. § Significant Characteristic
- 2. Dimensions D and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" per side.
- 3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-012B

5-Lead Plastic (ET) [DDPAK]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





| | MILLIMETERS | | | |
|----------------------------|-------------|----------|------|------|
| Dimensio | MIN | NOM | MAX | |
| Contact Pitch | E | .067 BSC | | |
| Optional Center Pad Width | X2 | | | .423 |
| Optional Center Pad Length | Y2 | | | .327 |
| Contact Pad Spacing | C1 | | .248 | |
| Contact Pad Width (X28) | X1 | | | .041 |
| Contact Pad Length (X28) | Y1 | | | .159 |

Notes:

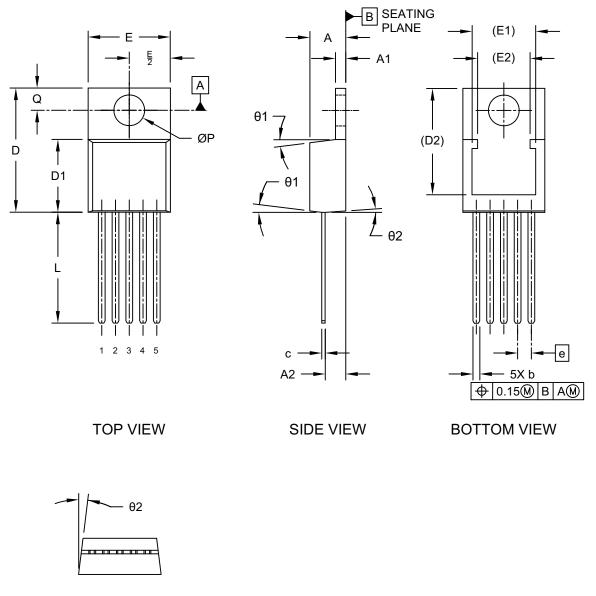
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2012A

5-Lead Transistor Outline Type LB03 (B8X) - [TO-220] Micrel Legacy Package TO220-LB03-5LD-PL-1

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

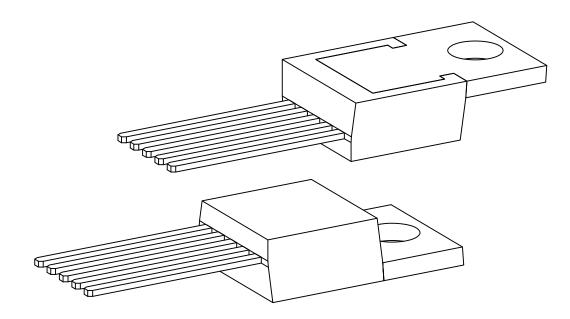


END VIEW

Microchip Technology Drawing C04-036-B8X Rev E Sheet 1 of 2

5-Lead Transistor Outline Type LB03 (B8X) - [TO-220] Micrel Legacy Package TO220-LB03-5LD-PL-1

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



| | INCHES | | | | |
|---------------------------------|--------|-----------|------|------|--|
| Dimension | Min | Nom | Max | | |
| Number of Leads | N | 5 | | | |
| Pitch | е | .067 BSC | | | |
| Overall Height | Α | .160 | .190 | | |
| Tab Height | A1 | .045 | .050 | .055 | |
| Seating Plane to Lead | A2 | .080 | .098 | .115 | |
| Lead Width | b | .025 | .033 | .040 | |
| Lead Thickness | С | .012 | .016 | .020 | |
| Lead Length | L | .500 | .540 | .580 | |
| Total Body Length Including Tab | D | .542 | .580 | .619 | |
| Molded Body Length | D1 | .348 | .354 | .360 | |
| Total Width | E | .380 | .400 | .420 | |
| Pad Width | E1 | 0.256 REF | | | |
| Pad Length | D2 | 0.486 REF | | | |
| Hole Diameter | ØР | .146 | .151 | .156 | |
| Hole Center to Tab Edge | Q | .103 | .108 | .113 | |
| Molded Body Draft Angle | θ1 | 3 | 7 | 10 | |
| Molded Body Draft Angle | θ2 | 1 | 4 | 7 | |

Notes:

Pin 1 visual index feature may vary, but must be located within the hatched area.
 Dimensioning and tolerancing per ASME Y14.5M

- - BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-036-B8X Rev E Sheet 2 of 2

APPENDIX A: REVISION HISTORY

Revision C (February 2024)

- Removed bold from maximum value of Output Leakage Current (Page 5).
- Updated the names of Figure 2-1, Figure 2-2 and Figure 2-12.
- Updated package name in Package Types.
- Updated Section 5.0, Packaging Information and Product Identification System.

Revision B (January 2022)

• Updated values and conditions for Enable Input Current in the Electrical Characteristics table.

Revision A (May 2018)

- Converted Micrel document MIC39300/01/02 to Microchip data sheet DS20006017A.
- Minor text changes throughout.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

| PART NO. | <u>-x.x</u> | ¥ | | <u>×</u> | <u>-XX</u> | Example | es: | |
|---|----------------------------------|---------------------------------------|---|--|---|----------|---|--|
| Device | Output Voltage | Juncti Tempera Rang 393xx: 3 | ature je | Package | Media Type | | 9300-1.8WT: | 3A, 1% Low-Voltage LDO Regulator, 1.8V Fixed Output Voltage, -40°C to +125°C Junction Temperature Range, RoHS Compliant*, 3-Lead TO-220 Package, 50/Tube |
| Device: | MIC: MIC: | 39300: F 39301: F F | ixed V _{OU} ixed V _{OU} lag + Shเ | T T with Enat | o LDO Regulato ole + Output Err LDO | b) MIC3 | 9300-2.5WT: | 3A, 1% Low-Voltage LDO Regulator, 2.5V Fixed Output Voltage, -40°C to +125°C Junction Temperature Range, RoHS Compliant*, 3-Lead TO-220 Package, 50/Tube |
| Output Voltage: Junction | x.x 1.8 2.5 blan | = 1.8\ = 2.5\ k= Adju | / / ustable (M | 9300/39301 11C39302) | | c) MIC39 | 9300-2.5WU: | 3A, 1% Low-Voltage LDO Regulator, 2.5V Fixed Output Voltage, -40°C to +125°C Junction Temperature Range, RoHS Compliant*, 3-Lead TO-263 Package, 50/Tube |
| Temperature Ran | T T U | = 3-Le = 5-Le = 3-Le | ead TO-22 ead TO-22 ead TO-26 | 20 (MIC393 20 (MIC393 53 (MIC393 | 801) 800) | d) MIC3 | 9300-2.5WU-TR: | 3A, 1% Low-Voltage LDO Regulator, 2.5V Fixed Output Voltage, -40°C to +125°C Junction Temperature Range, RoHS Compliant*, 3-Lead TO-263 Package, 750/Reel |
| Media Type¹: * RoHS compliar | U blan TR nt with "higł | (MIC k= 50/T = 750/ | C39301/3 [[] ube /Reel (TC |)-263, 3L ar | nd 5L) | e) MIC3 | 9301-1.8WT: | 3A, 1% Low-Voltage LDO Regulator with Enable, Output Error Flag + Shutdown, 1.8V Fixed Output Voltage, -40°C to +125°C Junction Temperature Range, RoHS Compliant*, 5-Lead TO-220 Package, 50/Tube |
| | | | | | | f) MIC39 | 301-1.8WU: | 3A, 1% Low-Voltage LDO Regulator with Enable, Output Error Flag + Shutdown, 1.8V Fixed Output Voltage, -40°C to +125°C Junction Temperature Range, RoHS Compliant*, 5-Lead DDPAK Package, 50/Tube |
| | | | | | | g) MIC3 | 9301-1.8WU-TR: | 3A, 1% Low-Voltage LDO Regulator with Enable, Output Error Flag + Shutdown, 1.8V Fixed Output Voltage, -40°C to +125°C Junction Temperature Range, RoHS Compliant*, 5-Lead DDPAK Package, 750/Reel |
| | | | | | | h) MIC3 | 9302WU: | 3A, 1 ^o Adjustable Wide VIN LDO, Adjustable Output Voltage (1.24V to 15.5V), -40°C to +125°C Junction Temperature Range, RoHS Compliant*, 5-Lead DDPAK Package, 50/Tube |
| | | | | | | i) MIC39 | 302WU-TR | 3A, 1% Adjustable Wide VIN LDO , Adjustable Output Voltage (1.24V to 15.5V), -40°C to +125°C Junction Temperature Range, RoHS Compliant*, 5-Lead DDPAK Package, 750/Reel |
| | | | | | | Note 1: | part number de ordering purpos package. Checl | identifier only appears in the catalog scription. This identifier is used for ses and is not printed on the device < with your Microchip Sales Office for bility with the Tape and Reel option. |

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